OPALE V2 Compact
SWap-C, trusted and flexible

Ready for OEM with Modified COTS services

As processing performance continues to improve, ECRIN Systems is dedicated to minimize the SWaP-C envelope of OPALE V2 series. High-end computing performance in a 2U chassis with a depth under 20” (492mm), OPALE V2 Compact fits most any 19” rack mount space. It will be particularly useful when footprint, performance, reliability and longevity are not optional: military shelter base station, rugged servers for harsh environments, simulator, telemetry, telecom, medical imaging, infotainment, control/command station, test bench system, Internet appliance...

Distinctively customized oriented thanks to our in-house design center, ECRIN Systems will help to personalize your computer and give you competitive advantage in the industrial world.

To precisely meet your requirements, even for small quantities, ECRIN takes full system development responsibility and guarantee long term availability to allow you to concentrate on your added value. From mechanical parts to industrial design, with front and remote user interfaces, user LED’s and I/O’s, easy customized front and rear connectors, specific face-plate color and design, Lexan polycarbonate sheet with your logo and brand name, we will offer you a unique look that will shape your image and promote your sales.

Drop shipping is available to facilitate a rapid, more convenient deployment directly to your end customers.

- Modified COTS with easy brand naming, configuration and customization for competition advantage
- Security with trusted boot
- Local and remote active management to detect errors before they occur
- Enhanced asset protection for continuous operation:
  - Durable connectors: 15 microinch Gold/Metal plated connectors assure long term reliability
  - Enhanced USB compatibility: USB power supply ensures stability (5V +/-5%)
  - Rugged EMI construction: EN55032 Class B Radiation test, -10dB than competition Class A
- MIL-STD tests passed (for T°C, shocks & vibrations, humidity, noise)
- Efficient thermal concept to get higher MTBF
- Reduced TCO with reporting log file and downtime in harsh environments
- Energy efficient design / Low noise
- Long life management: up to 10 years with revision control
- Advanced Multi-Core “Skylake” boosted computing performance with DDR4 speeds and timings
- Expandability with 4 full-height and full-length I/O cards into PICMG 1.3 butterfly backplane
OPALE V2 Compact

Rear I/O
- 1 x 3.5'' front accessible drive bay free - SLC and/or MLC Solid State Drive (32 Go ~ 2To)
- 1 x 2.5'' SATA Removable Drive

Drives
- Embedded M4, 4 LEDs with I/O capabilities

Rear I/O (behind door)
- 2 x USB 2.0

Cards lock
- Retaining bracket for cards

Packaging (W x H x D)
- Black: LCD 2x16 characters
- A: Single door with 2x Thumbscrews
- E: 4x tri-color LEDs
- B: 2x USB
- F: 2x USB
- C: Keyboard (Power & Restart)
- G: 3.5'' drive bay
- D: Lexan for easy customization

Form factor
- PICMG 1.3 - Graphic Class / Server Class – PCI Express Gen 3

Chipset
- Intel® Q770 Express chipset supporting PCI Express 3.0

Memory
- Dual-channel DDR4-2133 up to 32 GB (2* DIMM)

Video
- Integrated Intel® HD Graphics (VGA and DVI-D internal)

BIOS
- AMI® UEFI BIOS; 128 Mbit SPI Flash Memory

Ethernet
- 2 x GbE (Intel® I217-V)
- Intel® AMT and Wake On LAN support

Disk
- 4x SATA 6Gb/s ports

Audio Codec
- Intel® Rapid Storage Technology, supports RAID 0/1/5/10

USB
- 8x USB 3.0, 4x USB 2.0 (on backplane)

Watchdog timer
- 24~65535 sec software programmable, can generate system reset

Hardware monitor
- CPU & System temperature, fan speed and onboard DC voltages

Manageability
- SEMA support with BMC, SEMA cloud

SSL Trusted boot
- 1x boot header for TPM module (optional) - Atmel ATF9753CS204 TIS 1.2

I/O peripherals
- Serial port: 2x RS-232, 2x RS-232/422/485
- Parallel port: 1x LPT port via onboard box header
- USB: 4x USB 2.0

Environmental specifications
- Operating: 0~50°C (MIL STD 810 G, method 502.5 / 501.5) - Storage: -20~80°C
- Humidity: Operating: 5% to 90% non condensing

System Monitoring and Management
- Intel® AMT for remote management
- Local control with embedded MMI (Windows & Linux services)
- FAN control & monitoring
- System & network information
- Watchdog & elapsed time counter
- CPU & System temperature, fan speed and onboard DC voltages

Standard configuration
- Intel® Core™ i3-6100TE (2C/4T, 2.7 GHz, 4M Cache, 14nm, 35W TDP)
- Intel® Core™ i5-6500TE (4C/4T, 2.3 GHz, 6M Cache, 14nm, 35W TDP)
- Intel® Core™ i7-6700TE (4C/8T, 2.4 GHz, 8M Cache, 14nm, 35W TDP)

OEM services
- Branding user’s Lexan – Costless, NRE fees only
- Modified COTS customization:
  - Front panel design
  - Specific I/O on front panel / special connectors on rear panel
  - Specific H/W configurations
  - Specific S/W functionality

Power Supply Unit
- ATX 12V ~ 400W - High Efficiency 80+ 
- 90% - 240 VAC full range / 47-63 Hz
- 5VSB, 12V, +12V, -12V, +5V, -5V, +3.3V, -3.3V
- Option for 2x 420W mini-Redundant 2U PS

Backplane specifications
- EBP-D5E2 in standard configuration

Supports
- Microsoft® Windows® 7 32/64-bit, Windows 8 & 10 64-bit - Linux 32/64-bit

Conversion options
- Options
- Power Supply Unit
- Processor
- Memory
- Disk
- OS

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